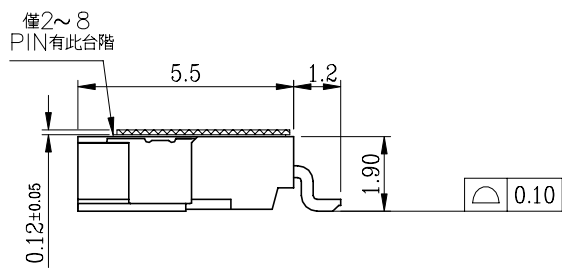
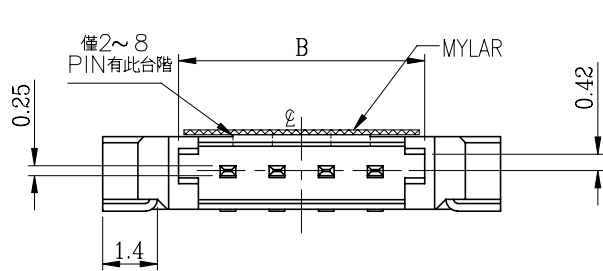


RECOMMENDED P.C. BOARD PATTERN DIM. (REF.)



- NOTES:
- MATERIAL:
 - HOUSING: HALOGEN FREE PLASTIC,UL94V-0.
 - CONTACT: COPPER ALLOY
 - FITTING NAIL: COPPER ALLOY
 - FINISH:
 - CONTACT:
 - 50 μ ~100 μ NICKEL UNDER PLATING OVER ALL GOLD FLASH ON CONTACT AREA
 - 50 μ ~100 μ NICKEL UNDER PLATING OVER ALL 80 μ ~120 μ PURE TIN ON CONTACT AREA
 - 50 μ ~100 μ NICKEL UNDER PLATING OVER ALL 80 μ ~120 μ MATT TIN ON CONTACT AREA
 - 50 μ ~100 μ NICKEL UNDER PLATING OVER ALL 15 μ MIN GOLD ON CONTACT AREA
 - 100 μ ~150 μ NICKEL UNDER PLATING OVER ALL 15 μ MIN GOLD ON CONTACT AREA
 - 100 μ ~150 μ NICKEL UNDER PLATING OVER ALL 30 μ MIN GOLD ON CONTACT AREA
 - 100 μ ~150 μ NICKEL UNDER PLATING OVER ALL 10 μ MIN GOLD ON CONTACT AREA
 - SOLDER:
 - 50 μ ~100 μ NICKEL UNDER PLATING OVER ALL GOLD FLASH ON SOLDER AREA
 - 50 μ ~100 μ NICKEL UNDER PLATING OVER ALL 80 μ ~120 μ PURE TIN ON SOLDER AREA
 - 50 μ ~100 μ NICKEL UNDER PLATING OVER ALL 80 μ ~120 μ MATT TIN ON SOLDER AREA
 - 50 μ ~100 μ NICKEL UNDER PLATING OVER ALL GOLD FLASH ON SOLDER AREA
 - 100 μ ~150 μ NICKEL UNDER PLATING OVER ALL GOLD FLASH ON SOLDER AREA
 - 100 μ ~150 μ NICKEL UNDER PLATING OVER ALL GOLD FLASH ON SOLDER AREA
 - 3 μ GOLD ON CONTACT GOLD FLASH ON SOLDER AREA
 - FITTING NAIL:
 - 50 μ ~100 μ NICKEL UNDER PLATING OVER ALL GOLD FLASH ON SOLDER TAILS
 - 50 μ ~100 μ NICKEL UNDER PLATING OVER ALL 100 μ ~150 μ PURE TIN ON SOLDER TAILS
 - 50 μ ~100 μ NICKEL UNDER PLATING OVER ALL 100 μ ~150 μ MATT TIN ON SOLDER TAILS
 - REFLOW SOLDER CAPABLE TO 260°C
 - PER ACES SPEC.
 - SPEC. PLS. REFER TO PS-50278-xxxx-xxx
 - PACKAGE PLS. REFER TO 88230-XX0X-TRP
 - PART NUMBER

P/N LEGEND	XXX	COLOR	PACKING
50278-XXX X X-XXX	001	BLACK	88230-XX0X-TRP
	002	NATURE	88230-XX0X-TRP
	003	BLACK	88230-XX0X-U-TRP

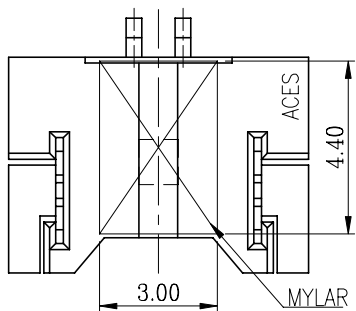
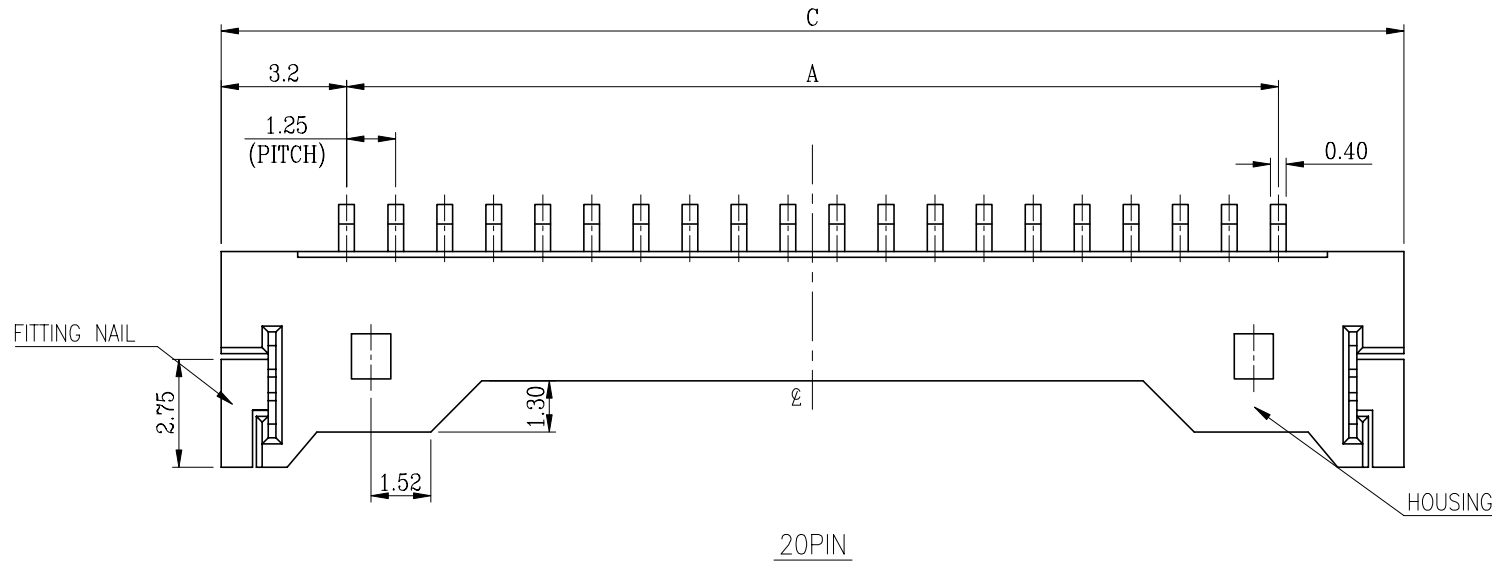
- PLATING
- L: PURE TIN
 - 1: GOLD FLASH
 - N: MATT TIN
 - C: CONTACT AREA:15 μ GOLD PLATING SOLDER AREA: GOLD FLASH
 - W: CONTACT AREA:15 μ GOLD PLATING SOLDER AREA: GOLD FLASH
 - D:30 μ GOLD ON CONTACT(LEAD FREE) SOLDER AREA: GOLD FLASH
 - T:10 μ GOLD ON CONTACT(LEAD FREE) SOLDER AREA: GOLD FLASH
 - A:3 μ GOLD ON CONTACT(LEAD FREE) SOLDER AREA: GOLD FLASH

CKT.	DIM A	DIM B	DIM C	M/s(W) \pm 0.10
2	1.25	3.77	7.65	3.00
3	2.50	5.02	8.90	3.00
4	3.75	6.27	10.15	6.00
5	5.00	7.52	11.40	6.00
6	6.25	8.77	12.65	6.00
7	7.50	10.02	13.90	10.00
8	8.75	11.27	15.15	10.00
9	10.00	12.52	16.40	10.00
10	11.25	13.77	17.65	12.00
11	12.50	15.02	18.90	X
12	13.75	16.27	20.15	X
14	16.25	18.77	22.65	X
15	17.50	20.02	23.90	X
16	18.75	21.27	25.15	X

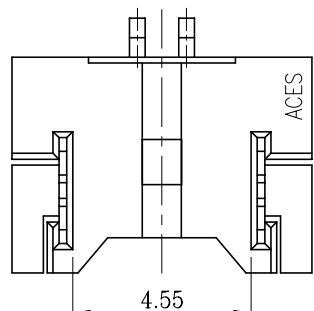
QUALITY SYMBOLS		DRAWN BY		DATE	
MAJOR \oplus		TIANYINGHONG		21/05/18	
CRITICAL \otimes		CHECKED BY		DATE	
GENERAL TOLERANCES (UNLESS SPECIFIED)		XUZHUYONG		21/05/18	
X. \pm 0.5		APPROVED BY		DATE	
X. \pm 0.25		XUZHUYONG		21/05/18	
.XX \pm 0.15		UNITS		SIZE	
.XXX \pm 0.1		mm		A4	
ANGLES \pm 2°		SCALE		REV	
		1:1		Q	
		SHEET NO.		RFQ NO.	
		1 OF 2		N/A	
		DWG NO.			
				50278-XXXXX-XXX	



TITLE
1.25mm WIRE TO BOARD CONN.
LPF-2 SMT R/A TYPE



2PIN WITH MYLAR



2PIN WITHOUT MYLAR

CKT.	DIM A	DIM B	DIM C	M/s(W)
20	23.75	26.27	30.15	X

QUALITY SYMBOLS MAJOR Ⓢ CRITICAL Ⓢ GENERAL TOLERANCES (UNLESS SPECIFIED) X ±0.5 XX ±0.25 .XXX ±0.1 ANGLES ±2°	DRAWN BY TIANYINGHONG	DATE 21/05/18	
	CHECKED BY XUZHUYONG	DATE 21/05/18	
GENERAL TOLERANCES (UNLESS SPECIFIED) X ±0.5 XX ±0.25 .XXX ±0.1 ANGLES ±2°	APPROVED BY XUZHUYONG	DATE 21/05/18	TITLE 1.25mm WIRE TO BOARD CONN. LPF-2 SMT R/A TYPE
	UNITS mm		SIZE A4
SCALE 1:1	SHEET NO. 2 OF 2	REV Q	DWG NO. 50278-XXXXX-XXX

单击下面可查看定价，库存，交付和生命周期等信息

[>>ACES\(宏致\)](#)